

RE

03-19-2002



102020937

HEET

To the Honorable Commissioner of Patents and Trademarks

ached original documents or copy thereof.

1. Name of conveying party(ies):
Michiyuki SHIMIZU

03/07/02

2. Name and address of receiving party(ies):
Name: Hitachi, Ltd.

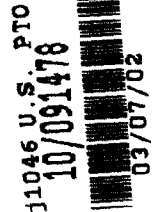
Street Address: 6, Kanda Surugadai 4-chome, Chiyoda-ku

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other _____
Execution Date: February 14, 2002

City: Tokyo

Country: Japan

Additional name(s) & address(es) attached? Yes No



4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: February 14, 2002
A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? Yes No

6. Total number of applications and patents involved: 1

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: ANTONELLI, TERRY, STOUT & KRAUS, LLP

Internal Address:

Street Address: 1300 North Seventeenth Street
Suite 1800

City: Arlington State: VA Zip: 22209

7. Total fee (37 CFR 3.41).....\$40.00
 Enclosed
 Any deficiencies may be charged to deposit account
 Authorized to be charged to deposit account

8. Deposit account number: 01-2135

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William I. Solomon *William I. Solomon* March 7, 2002
Name of Person Signing Signature Date
Attorney Registration No. 28,565
Total number of pages including cover sheet, attachments, and document: 2

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

FABRICATION METHOD OF SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Michiyuki SHIMIZU; Michiyuki SHIMIZU</u>	<u>14 / February / 2002</u>
2) _____	_____
3) _____	_____
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____